

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1-20. (Canceled)

21. (Currently Amended) An apparatus comprising:

a mounting board, on which ~~having an insulated surface with~~ a plurality of conductive patterns ~~being are~~ formed thereon via an insulating layer;

a hybrid integrated circuit, disposed on the mounting board, and incorporating at least one conductive path, an active element and a passive element electrically connected to the conductive path, wherein the conductive path, the active element, and the passive element are sealed by an insulating resin; ~~having at least one conductive path and disposed on the mounting board;~~ and

wherein a rear surface of said at least one conductive path is exposed at a surface of the insulating resin; and

an insulating film selectively formed on [[a]] the rear surface of the at least one conductive path such that at least one of the conductive patterns located at a top part of the mounting board is insulated from the at least one conductive path ~~hybrid integrated circuit to insulate the conductive paths from at least some of the conductive patterns.~~

22. (Currently Amended) The apparatus ~~[[of]]~~ according to claim 21, wherein the at least one conductive path sealed by the insulating film intersects with the conductive pattern which is located at the top part of the mounting board, ~~at least one conductive path and conductive patterns in certain locations cross without making contact.~~

23. (Currently Amended) The apparatus ~~[[of]]~~ according to claim 21, wherein said at least one active element is connected to the conductive path by a metal wiring, ~~further comprising at least one semiconductor element coupled to the conductive paths by fine metal wires.~~

24. (Currently Amended) The apparatus ~~[[of]]~~ according to claim 21 ~~claim 23~~ wherein the hybrid integrated circuit is mounted on the mounting board such that said at least one of the conductive patterns is connected to at least one of the conductive paths, ~~at least one of the semiconductor elements, the fine metal wires and the conductive paths are integrally molded as a single package and disposed on the mounting board to couple the conductive path to at least one of the conductive patterns.~~

25. (Currently Amended) The apparatus ~~[[of]]~~ according to claim 21, wherein the insulating ~~[[film]]~~ layer comprises a solder resist.

26. (Currently Amended) The apparatus ~~[[of]]~~ according to claim 21, wherein the mounting board is one of a printed circuit board, a ceramic board ~~substrate~~, a flexible sheet substrate or a metal board ~~metallic substrate~~.

27. (Currently Amended) An apparatus comprising:

a mounting board, on which a plurality of patterns are formed via an insulated layer
~~having an insulated surface with a plurality of conductive patterns being formed thereon;~~

one or more semiconductor devices ~~each having at least one conductive path and~~
disposed on the mounting board, each semiconductor device comprising at least one conductive
path and a semiconductor element electrically connected to the conductive path, wherein the
conductive path and the semiconductor element are sealed by an insulating resin; and

an insulating film selectively formed on a rear surface of the conductive path such that
the conductive pattern located at a top part of the mounting board is insulated from the
conductive path. ~~each of the one or more semiconductor devices to insulate the conductive paths~~
~~from at least some of the conductive patterns.~~

28. (Currently Amended) The apparatus ~~[[of]]~~ according to claim 27, wherein the conductive
path sealed by the insulating film intersects with the conductive pattern which is located at the
top part of the mounting board. ~~at least one conductive path and conductive patterns in certain~~
~~locations cross without making contact.~~

29. (Currently Amended) The apparatus ~~[[of]]~~ according to claim 27, wherein said at least one active element is connected to the conductive path by a metal wiring, ~~further comprising at least one semiconductor element coupled to the conductive paths by fine metal wires.~~

30. (Currently Amended) The apparatus of claim 29, wherein the semiconductor device is mounted on the mounting board such that said at least one conductive pattern is connected to the at least one conductive path. ~~at least one of the semiconductor elements, the fine metal wires and the conductive paths are integrally molded as a single package and disposed on the mounting board to couple the conductive path to at least one of the conductive patterns.~~

31. (Currently Amended) The apparatus ~~[[of]]~~ according to claim 27, wherein the insulating film comprises a solder resist.

32. (Currently Amended) The apparatus ~~[[of]]~~ according to claim 27 wherein the mounting board is one of a printed circuit board, a ceramic board ~~substrate~~, a flexible sheet substrate or a metal board ~~metallic substrate~~.

33. (Currently Amended) A method comprising:

forming a plurality of conductive patterns on a mounting board via an insulated layer ~~having an insulated surface;~~

selectively-forming an insulating film on a rear surface of a semiconductor device which is sealed by an insulating resin and includes a conductive path exposed at one surface of the insulating resin, so as to selectively cover the conductive path ~~hybrid integrated circuit having~~
~~conductive paths; and~~

mounting the semiconductor device on the mounting board such that the insulating layer insulates the conductive path from at least some of the conductive patterns. ~~disposing the hybrid~~
~~integrated on the mounting board,~~

~~wherein the insulating film insulates the conductive paths from at least some of the~~
~~conductive patterns.~~

34. (New) The apparatus according to claim 21, wherein the at least one conductive path includes a wiring for electrically connecting between a conductive path on which the active element is mounted, and a conductive path on which the passive element is mounted.

35. (New) The apparatus according to claim 23, wherein the at least one conductive path comprises a wiring for electrically connecting between the conductive paths connected to the metal wiring.

36. (New) The apparatus according to claim 23, wherein the at least one conductive path comprises a wiring for electrically connecting a conductive path connected to the metal wiring and a conductive path on which the active element or the passive element is mounted.